

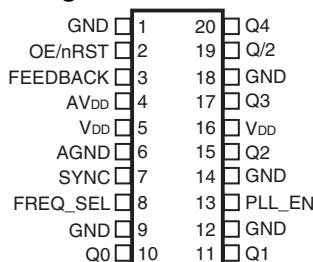
General Description

The 870931I-01 is an LVCMS clock generator that uses an internal phase lock loop (PLL) for frequency multiplication and to lock the low-skew outputs to the reference clock. The device offers six outputs. The PLL loop filter is completely internal and does not require external components. Several combinations of the PLL feedback and a divide-by-2 (controlled by FREQ_SEL) allow applications to optimize frequency generation over a wide range of input reference frequencies. The PLL can also be disabled by the PLL_EN control signal to allow for low frequency or DC testing. The 870931I-01 device is a member of the family of high performance clock solutions from IDT.

Features

- Single-ended input reference clock
- Six single-ended clock outputs
- Internal PLL does not require external loop filter components
- 5V tolerant inputs
- Maximum output frequency: 80MHz, (Q0:Q4 outputs)
- Maximum output frequency: 40MHz, (Q/2 output)
- LVCMS interface levels for all inputs and outputs
- PLL disable feature for low-frequency testing
- Output drive capability: $\pm 24\text{mA}$
- Output skew: 300ps (maximum), Q0:Q4 and Q/2
- Full 3.3V supply voltage
- Available in lead-free packages
- -40°C to 85°C ambient operating temperature
- Fully pin and function compatible with the IDTQS5LV931 (including 50, 66 and 80MHz options)

Pin Assignment



870931I-01

20-Lead QSOP, 150Mil

3.9mm x 8.65mm x 1.5mm package body

R Package

Top View

Block Diagram

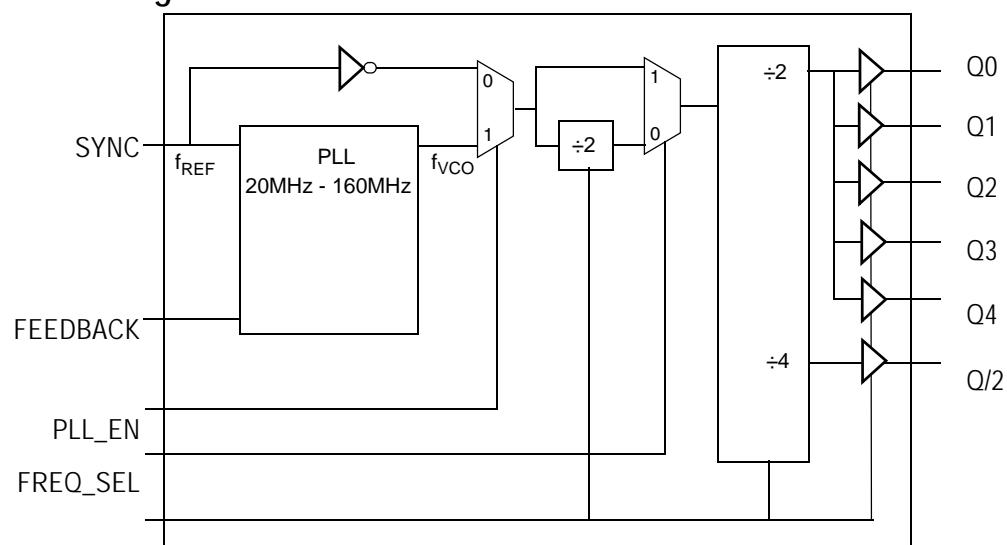


Table 1. Pin Descriptions

| Number | Name | Type | Description |
|-----------------------|-----------------------|--------|---|
| 1, 9, 12, 14, 18 | GND | Power | Power supply ground. |
| 2 | OE/nRST | Input | Output enable and asynchronous reset. Resets all outputs. Logic LOW, the outputs are in high-impedance state. Logic HIGH enables all outputs. LVCMS/LVTTL interface levels. |
| 3 | FEEDBACK | Input | PLL feedback input which is connected to one of the clock outputs to close the PLL feedback loop. LVCMS/LVTTL interface levels. |
| 4 | AV _{DD} | Power | Positive power supply for the PLL. |
| 5, 16 | V _{DD} | Power | Positive power supply pins. |
| 6 | AGND | Power | Power supply ground for the PLL. |
| 7 | SYNC | Input | Single-ended reference clock input. LVCMS/LVTTL interface levels. |
| 8 | FREQ_SEL | Input | Frequency select. Logic LOW level inserts a divide-by-2 into the PLL output and feedback path. Logic HIGH inserts a divide-by-1 into the PLL output and feedback path. LVCMS/LVTTL interface levels. |
| 10, 11, 15, 17, 20 | Q0, Q1, Q2, Q3, Q4 | Output | Single-ended clock outputs. LVCMS/LVTTL interface levels. |
| 13 | PLL_EN | Input | PLL enable. Enable and disables the PLL. Logic HIGH enables the PLL. Logic LOW disables the PLL and the input reference signal is routed to the output dividers (PLL bypass). LVCMS/LVTTL interface levels. |
| 19 | Q/2 | Output | Single-ended clock output. LVCMS/LVTTL interface levels. |

Table 2. Pin Characteristics

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|------------------|-------------------------------|---|---------|---------|---------|-------|
| C _{IN} | Input Capacitance | | | 4 | | pF |
| C _{PD} | Power Dissipation Capacitance | V _{DD} = AV _{DD} = 3.6V | | 330 | | pF |
| R _{OUT} | Output Impedance | | | 11 | | Ω |

Device Configuration

The 870931I-01 requires a connection to one of the clock outputs to the FEEDBACK input to close the PLL feedback path. The selection of the output (output divider) for PLL feedback will impact the device configuration and input to output frequency ratio and frequency ranges. See [Table 3D](#) for details.

Function Tables

Table 3A. OE/nRST Mode Configuration Table

| Input | Operation |
|---------|--|
| OE/nRST | |
| 0 | Device is reset and the outputs Q0:Q4 and Q/2 are in high-impedance state. This control is asynchronous. |
| 1 | Outputs are enabled. |

Table 3B. FREQ_SEL Mode Configuration Table

| Input | Operation |
|----------|--|
| FREQ_SEL | |
| 0 | The VCO output is frequency-divided by 2. This setting allows for a lower input frequency range. See also table 3D for available frequency ranges. |
| 1 | The VCO output is frequency-divided by 1. This setting allows for a higher input frequency range. See also table 3D for available frequency ranges. |

Table 3C. PLL_EN Mode Configuration Table

| Input | Operation |
|--------|---|
| PLL_EN | |
| 0 | The PLL is bypassed. The input reference clock is routed to the output dividers for low-frequency board test purpose. The PLL-related AC specifications do not apply in PLL bypass mode. |
| 1 | The PLL is enabled and locks to the input reference signal. |

Table 3D. Frequency Configuration Table

| Outputs Used for PLL Feedback | FREQ_SEL | Input Frequency Range (MHz) | Output Frequency Range (MHz) and Output-to-Input Frequency Multiplication Factor | |
|-------------------------------|----------|-----------------------------|--|-----------------|
| | | SYNC | Q[0:4] | Q/2 |
| Q0, Q1, Q2, Q3 or Q4 | 0 | 5 - 40 | 5 - 40 (1x) | 2.5 - 20 (0.5x) |
| | 1 | 10 - 80 | 10 - 80 (1x) | 5 - 40 (0.5x) |
| Q/2 | 0 | 2.5 - 20 | 5 - 40 (2x) | 2.5 - 20 (1x) |
| | 1 | 5 - 40 | 10 - 80 (2x) | 5 - 40 (1x) |

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

| Item | Rating |
|--|--------------------------|
| Supply Voltage, V_{DD} | 4.6V |
| Inputs, V_I | -0.5V to $V_{DD} + 0.5V$ |
| Outputs, V_O | -0.5V to $V_{DD} + 0.5V$ |
| Package Thermal Impedance, θ_{JA} | 72.3°C/W (0 lfpm) |
| Storage Temperature, T_{STG} | -65°C to 150°C |

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, $V_{DD} = AV_{DD} = 3.3V \pm 0.3V$, $T_A = -40^\circ C$ to $85^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|----------------------|--------------------------------|---|---------|---------|---------|-------|
| V_{DD} , AV_{DD} | Positive Supply Voltage | | 3.0 | 3.3 | 3.6 | V |
| I_{DDQ} | Quiescent Power Supply Current | $V_{DD} = AV_{DD} = \text{Max.}$, $OE/nRST = 0$, $SYNC = 0$, All Outputs Open | | | 5 | mA |

Table 4B. LVCMS/LVTTL DC Characteristics, $V_{DD} = AV_{DD} = 3.3V \pm 0.3V$, $T_A = -40^\circ C$ to $85^\circ C$

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|----------|------------------------|---|---|---------|----------------|---------|
| V_{IH} | Input High Voltage | | 2 | | $V_{DD} + 0.3$ | V |
| V_{IL} | Input Low Voltage | | -0.3 | | 0.8 | V |
| I_{IH} | Input High Current | SYNC, OE/nRST, FEEDBACK, PLL_EN, FREQ_SEL | $V_{DD} = V_{IN} = 3.3V$ | | 5 | μA |
| I_{IL} | Input Low Current | SYNC, OE/nRST, FEEDBACK, PLL_EN, FREQ_SEL | $V_{DD} = 3.3V$, $V_{IN} = 0V$ | -5 | | μA |
| V_{OH} | Output High Voltage: | Q0:Q4, Q/2 | $I_{OH} = -24\text{ mA}$ | 2.6 | | V |
| V_{OL} | Output Low Voltage | Q0:Q4, Q/2 | $I_{OL} = 24\text{ mA}$ | | 0.5 | V |
| I_{OZ} | Output Leakage Current | Q0:Q4, Q/2 | OE/nRST = 0, $V_{OUT} = 0V$ or V_{DD} , $V_{DD} = 3.6V$ | | ± 5 | μA |

Table 5. AC Electrical Characteristics, $V_{DD} = AV_{DD} = 3.3V \pm 0.3V$, $T_A = -40^\circ\text{C}$ to 85°C

| Symbol | Parameter | Test Conditions | | Minimum | Typical | Maximum | Units |
|--------------------|--|---------------------------------|-------------|----------------------|---------|----------------------|-------|
| f_{REF} | SYNC Input Reference Frequency | Feedback of Q0:Q4, FREQ_SEL = 0 | | 5 | | 40 | MHz |
| | | Feedback of Q0:Q4, FREQ_SEL = 1 | | 10 | | 80 | MHz |
| | | Feedback of Q/2, FREQ_SEL = 0 | | 2.5 | | 20 | MHz |
| | | Feedback of Q/2, FREQ_SEL = 1 | | 5 | | 40 | MHz |
| f_{OUT} | Output Frequency | Q0-Q4 | | | | 80 | MHz |
| | | Q/2 | | | | 40 | MHz |
| idc | Input Duty Cycle | SYNC | | 25 | | 75 | % |
| t_R / t_F | Input Rise/ Fall Time | SYNC | | | | 3 | ns |
| tsk(o) | Output Skew; NOTE 1, 2, 3 | Rising edges of Q0:Q4 and Q/2 | | | | 300 | ps |
| | Output Skew; NOTE 1, 2, 3 | Falling edges of Q0:Q4 | | | | 300 | ps |
| t_{PW} | Output Pulse Width | Q0:Q4 | 80MHz | $t_{PERIOD}/2 - 0.5$ | | $t_{PERIOD}/2 + 0.5$ | ns |
| | | Q/2 | 40MHz | $t_{PERIOD}/2 - 0.4$ | | $t_{PERIOD}/2 + 0.4$ | ns |
| tjit(cc) | Cycle-to-Cycle Jitter | Feedback = Q | | | | 320 | ps |
| | | Feedback = Q/2 | | | | 530 | ps |
| t(ϕ) | Static Phase Offset, (SYNC to FEEDBACK delay); NOTE 2, 4 | Q0:Q4 | 80MHz | -500 | | 500 | ps |
| t_{PZL} | Output Enable Time; NOTE 5 | OE/nRST | Low-to-High | | | 14 | ns |
| t_{PHZ}, t_{PLZ} | Output Disable Time; NOTE 5 | OE/nRST | High-to-Low | | | 14 | ns |
| t_R / t_F | Output Rise/ Fall Time | Q0:Q4, Q/2 | 0.8V – 2.0V | 0.2 | | 2 | ns |
| t_{LOCK} | PLL Lock Time | | | | | 10 | ms |

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at $V_{DD}/2$.

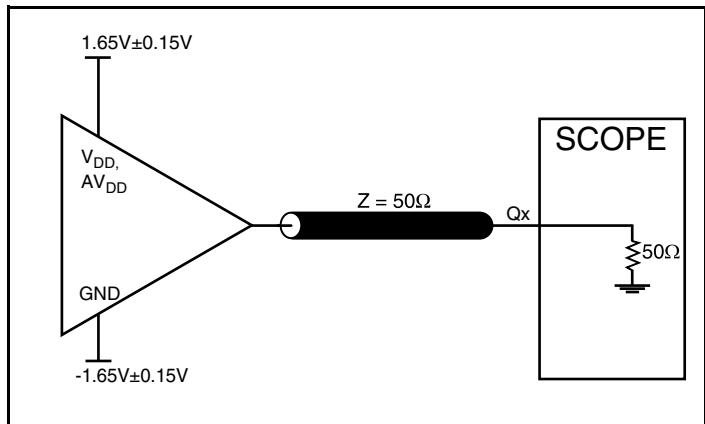
NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Measured between coincident rising output edges of Q0:Q4 and Q/2.

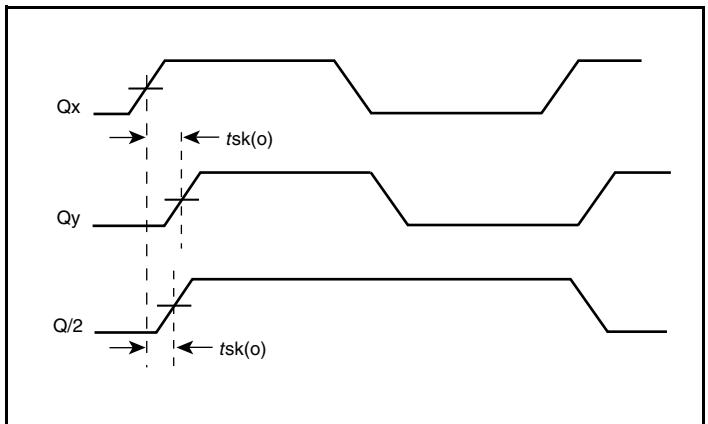
NOTE 4: Defined as the time difference between the input reference clock and the average feedback input signal when the PLL is locked and the input reference frequency is stable.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

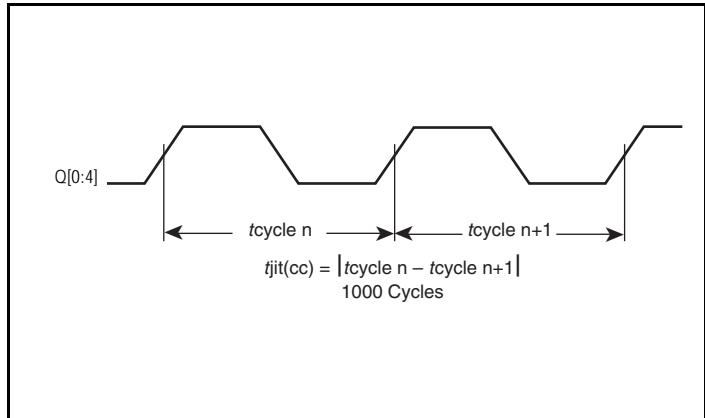
Parameter Measurement Information



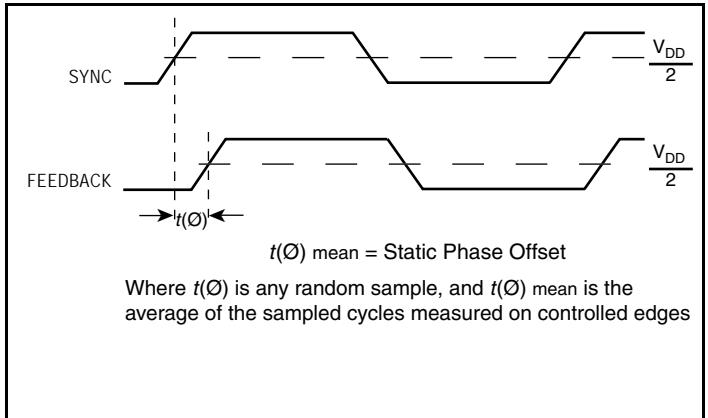
3.3V Output Load AC Test Circuit



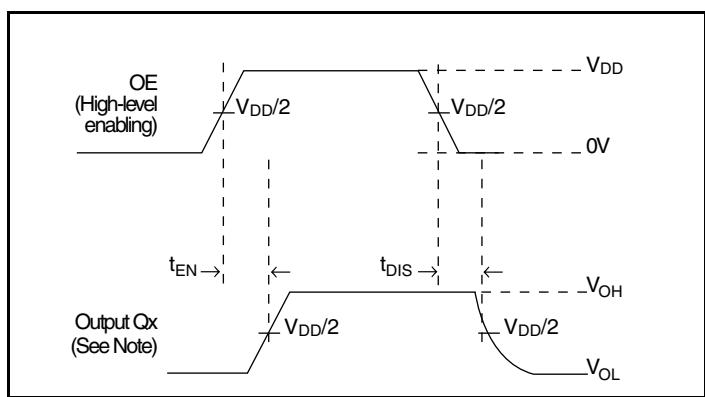
Output Skew



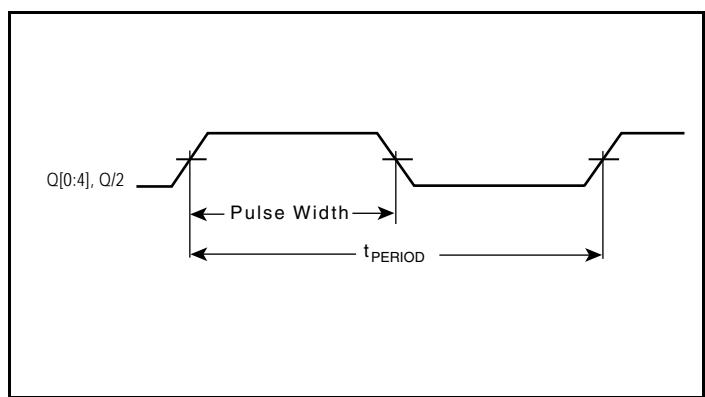
Cycle-to-Cycle Jitter



Static Phase Offset

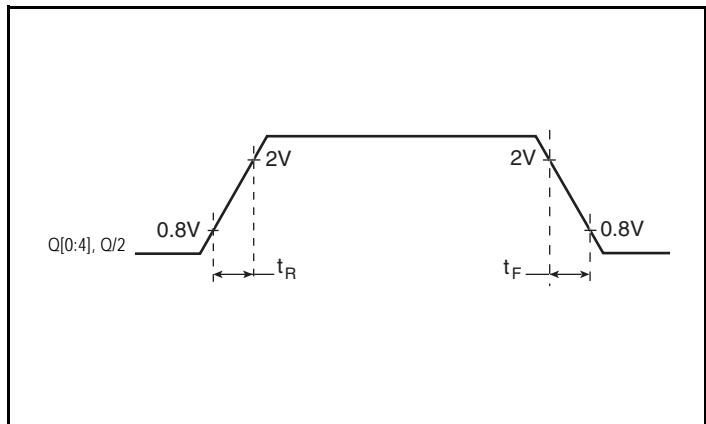


Output Enable/Disable



Output Pulse Width

Parameter Measurement Information, continued



Output Rise/Fall Time

Application Information

Recommendations for Unused Output Pins

Outputs:

LVC MOS Outputs

All unused LVC MOS output can be left floating. There should be no trace attached.

Schematic Example

Figure 1 shows an example of an 870931I-01 application schematic. In this example, the device is operated at $V_{DD} = 3.3V$. The decoupling capacitors should be located as close as possible to the

power pin. The input is driven by a 3.3V LVC MOS driver. An example of LVC MOS termination is shown in this schematic.

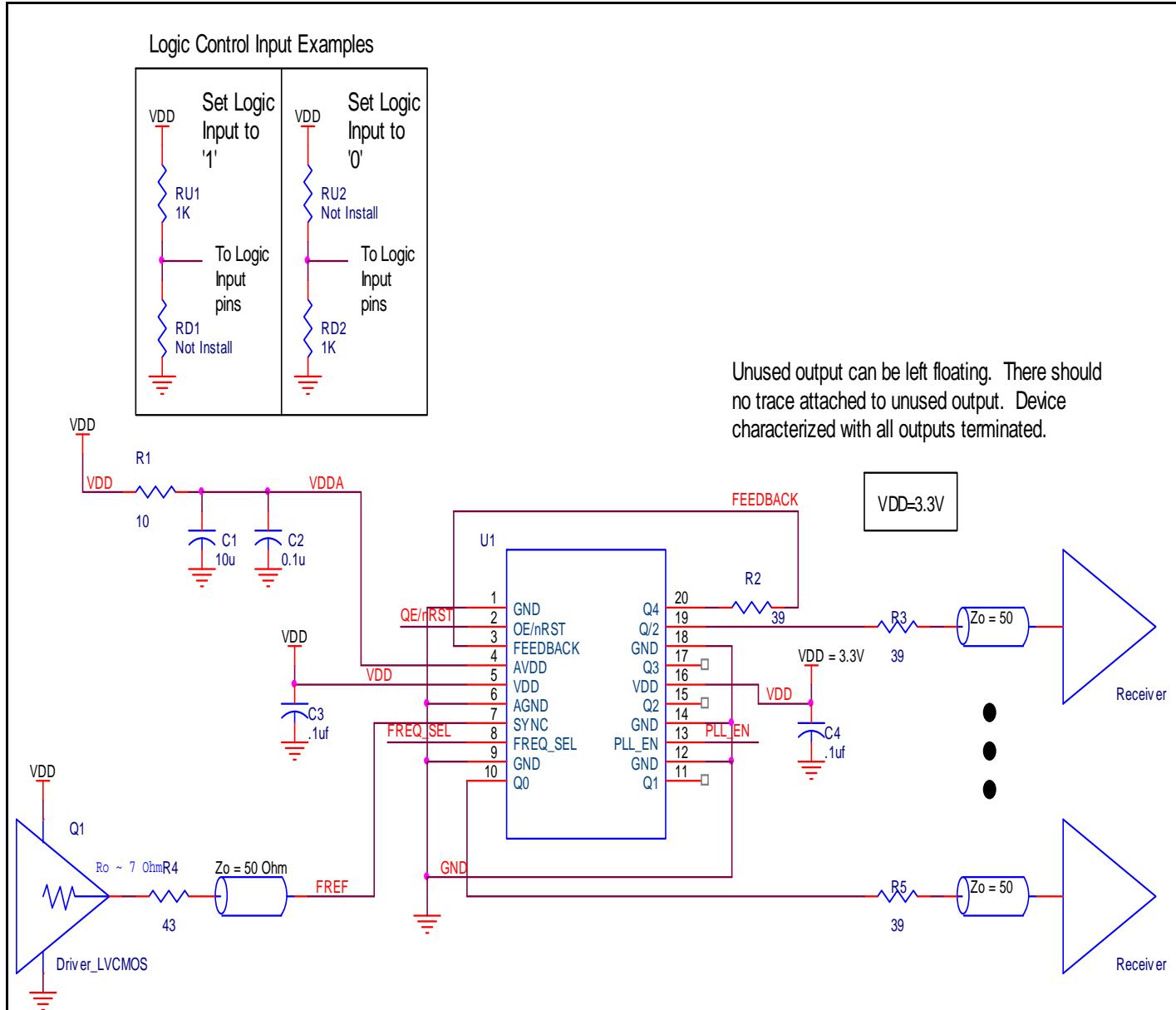


Figure 1. 870931I-01 Schematic Layout Example

Power Considerations

This section provides information on power dissipation and junction temperature for the 870931I-01. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the 870931I-01 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{DD} = 3.3V + 0.3V = 3.6V$, which gives worst case results.

- Power (core)_{MAX} = $V_{DD_MAX} * I_{DD_MAX} = 3.6V * 5mA = 18mW$
- Output Impedance R_{OUT} Power Dissipation due to Loading 50Ω to $V_{DD}/2$
Output Current $I_{OUT} = V_{DD_MAX} / [2 * (50\Omega + R_{OUT})] = 3.6V / [2 * (50\Omega + 11\Omega)] = 29.5mA$
- Power Dissipation on the R_{OUT} per LVCMOS output
Power (R_{OUT}) = $R_{OUT} * (I_{OUT})^2 = 11\Omega * (29.5mA)^2 = 9.57mW$ per output
- Total Power (R_{OUT}) = R_{OUT} (per output) * number of outputs = $9.57mW * 6$ outputs = $57.42mW$

Dynamic Power Dissipation at 80MHz

$$\text{Power (80MHz)} = C_{PD} * \text{Frequency} * (V_{DD})^2 = 330pF * 80MHz * (3.6V)^2 = 342mW$$

Total Power

$$\begin{aligned} &= \text{Power (core)}_{MAX} + \text{Total Power} (R_{OUT}) + \text{Power (80MHz)} \\ &= 18mW + 57.42mW + 342mW \\ &= 417.42mW \end{aligned}$$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C .

The equation for T_j is as follows: $T_j = \theta_{JA} * P_{d_total} + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

P_{d_total} = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming no air flow and a multi-layer board, the appropriate value is 72.3°C/W per Table 6 below.

Therefore, T_j for an ambient temperature of 85°C with all outputs switching is:

$$85^\circ\text{C} + 0.417W * 72.3^\circ\text{C/W} = 115.1^\circ\text{C}. \text{ This is well below the limit of } 125^\circ\text{C}.$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 6. Thermal Resistance θ_{JA} for a 20 Lead QSOP, Forced Convection

| θ_{JA} by Velocity | | | |
|---|----------|----------|----------|
| Linear Feet per Minute | 0 | 200 | 500 |
| Multi-Layer PCB, JEDEC Standard Test Boards | 72.3°C/W | 64.4°C/W | 61.0°C/W |

Reliability Information

Table 7. θ_{JA} vs. Air Flow Table for a 20 Lead QSOP

| θ_{JA} vs. Air Flow | | | |
|---|----------|----------|----------|
| Linear Feet per Minute | 0 | 200 | 500 |
| Multi-Layer PCB, JEDEC Standard Test Boards | 72.3°C/W | 64.4°C/W | 61.0°C/W |

Transistor Count

The transistor count for 870931I-01: 1489

Package Outline and Package Dimensions

Package Outline - R Suffix for 20 Lead QSOP, 150MIL

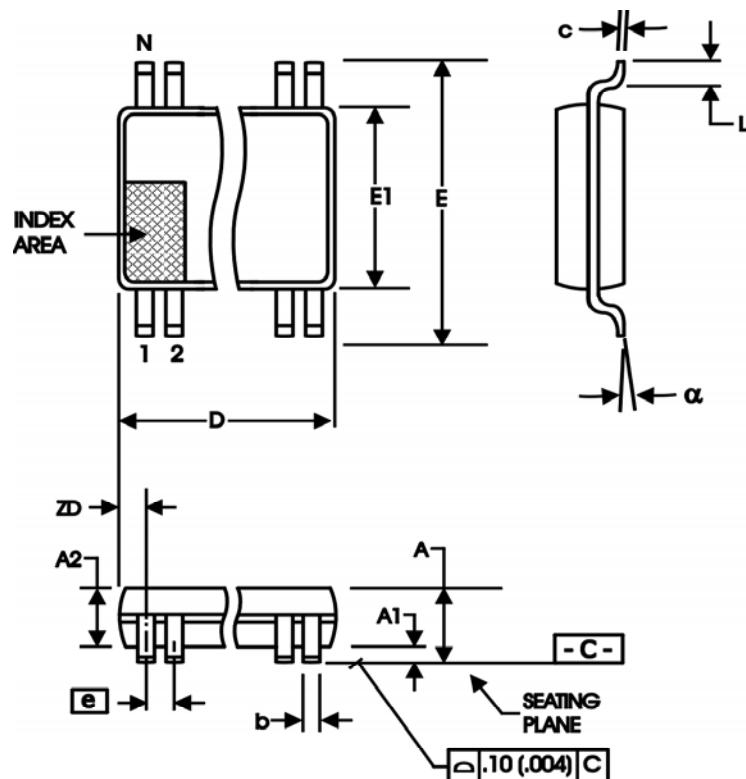


Table 8. Package Dimensions for 20 Lead QSOP

| All Dimensions in Millimeters | | |
|-------------------------------|-------------|---------|
| Symbol | Minimum | Maximum |
| N | 20 | |
| A | 1.35 | 1.75 |
| A1 | 0.10 | 0.25 |
| A2 | | 1.50 |
| b | 0.20 | 0.30 |
| c | 0.18 | 0.25 |
| D | 8.55 | 8.750 |
| E | 5.80 | 6.20 |
| E1 | 3.80 | 4.00 |
| e | 0.635 Basic | |
| L | 0.40 | 1.27 |
| α | 0° | 8° |
| ZD | 1.47 Ref | |

Reference Document: JEDEC Publication 95, MO-137

Ordering Information

Table 9. Ordering Information

| Part/Order Number | Marking | Package | Shipping Packaging | Temperature |
|-------------------|-------------|--------------------------|--------------------|---------------|
| 870931ARI-01LF | 870931AI01L | “Lead-Free” 20 Lead QSOP | Tube | -40°C to 85°C |
| 870931ARI-01LFT | 870931AI01L | “Lead-Free” 20 Lead QSOP | Tape & Reel | -40°C to 85°C |

Revision History Sheet

| Rev | Table | Page | Description of Change | Date |
|-----|-------|---------|---|----------|
| A | | 8 | Added Layout Schematic. | 6/10/09 |
| A | T9 | 11 | Removed leaded orderable parts from the Ordering Information table | 11/15/12 |
| A | T9 | 1 11 | Removed ICS from part number were needed. General Description - Deleted ICS Chip and HiperClocks. Ordering Information - Deleted LF note below table. Removed quantity for tape and reel. Updated header and footer. | 1/27/16 |
| B | | 1 | Corrected header title. | 4/25/16 |

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